This multiplexer features three-state outputs that can interface directly with and drive data lines of bus-organized systems. With all but one of the common outputs disabled (at a high-impedance state) the low impedance of the single enabled output will drive the bus line to a high or low logic level.

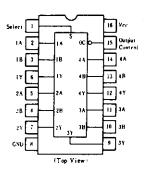
To minimize the possibility that two outputs will attempt to take a common bus to opposite logic levels, the output-enable circuitry is designed such that the output disable times are shorter than the output enable times.

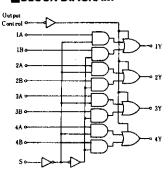
MABSOLUTE MAXIMUM RATINGS

Item	Symbol	Ratings	Unit
Supply voltage	Vcc	7.0	v
Input voltage	VIN	7.0	v
Output voltage (off-state)	Vowss	5.5	v
Operating temperature range	Topr	-20~+75	Ċ
Storage temperature range	Tete	-65~ +150	,c

PIN ARRANGEMENT

BBLOCK DIAGRAM





#FUNCTION TABLE

	0			
ос	S	A	В	Outputs
Н	×	×	×	Z
L	L	L	×	L
L	L	Н	×	н
L	Н	×	L	L
L	Н	×	Н	н

Note) H; high level, L; low level, X; irrelevant Z; off (high-impedance) state of a 3-state output

ELECTRICAL CHARACTERISTICS ($Ta = -20 \sim +75^{\circ}$ C)

1	tem	Symbol	Test Conditions		min	typ*	max	Unit
Input voltage		Vih			2.0	_		v
		VIL			_	_	0.8	V
		Voн	Vcc=4.75V, VIH=2V, VIL=0.8V	I, Iон = −2.6mA	2.4	_		v
Output voltage	e	**	$V_{CC} = 4.75 \text{V}, V_{IH} = 2 \text{V},$	IoL=8mA		_	0.5	v
		Vol	$V_{IL}=0.8V$	IoL = 4mA			0.4	
	S	Іін	V 5 25V V 2 7V		_		40	
	S except	11H	$V_{CC} = 5.25 \text{V}, V_I = 2.7 \text{V}$		_		20	μA
•	S	II.	$Vcc = 5.25V, V_I = 0.4V$		_		-0.8	mA
Input current	S except	II L			_		-0.4	
	S	Tı .	$V_{cc} = 5.25 \text{V}, V_I = 7 \text{V}$		_	_	0.2	
	S except	11	VCC-5.25V, VI-1V		_		0.1	mA
Output current		loz	$V_{CC} = 5.25 \text{V}, V_{IH} = 2 \text{V}$	Vo=2.4V	_	_	20	μΑ
		102	VCC-3.23V, VIH-2V	$V_0 = 0.4V$	_		- 20	
Short-circuit output current		I os	$V_{CC}=5.25V$		- 30		-130	mA
Supply current**	All outputs high					5.9	10	
	All outputs low	Icc	$V_{CC}=5.25V$		_	9.2	16	mА
	All outputs off				_	10	19	
Input clamp v	oltage	Vik	$V_{CC} = 4.75 \text{V}, I_{IN} = -18 \text{m}.$	A	-	_	-1.5	V

^{*} *V_{CC}*=5V, *Ta*=25°C

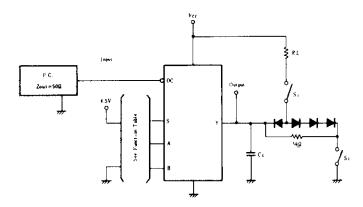
^{**} ICC is measured with all outputs open and all possible inputs grounded while achieving the stated output conditions.

ESWITCHING CHARACTERISTICS ($V_{CC} = 5V$, $T_a = 25^{\circ}C$)

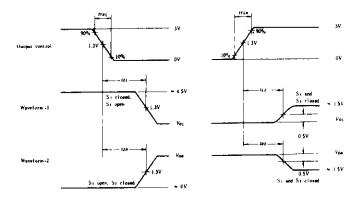
Item	Inputs	Output	Symbol	Test Conditions	min	typ	max	Unit
Propagation delay time		v	tri.n		-	12	18	
	A, B	Y	teht.	i		12	18	ns
		v	tp).H	$R_L = 2k \Omega$		14	21	
	S	Y	test.	$C_L = 15 \text{pF}$		14	21	ns
Output enable time		Y	tzн	- F		20	30	
	oc		1 21.	1 !		20	30	ns
Output disable time		.,	thz	$R_L = 2\mathbf{k} \Omega$		18	30	
	oc	Y	11.2	$C_L = 5pF$		16	25	ns

TESTING METHOD

1) Test Circuit



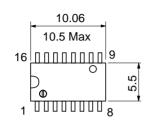
Waveform

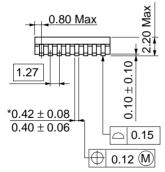


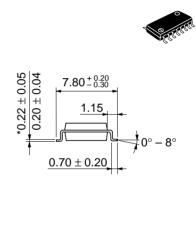
- Notes) 1. Input pulse: $t_{TLH} \le 15$ ns, $t_{THL} \le 6$ ns, PRR = 1MHz, duty cycle = 50%.
 - 2. C_L includes probe and jig capacitance.
 - 3. All diodes are 1S2074 (B).
 - Waveform-1 is for an output with internal conditions such that the output is low except when disabled by the output control.
 - Waveform-2 is for an output with internal conditions such that the output is high except when disabled by the output control.

Unit: mm 19.20 20.00 Max 16 7.40 Max 6.30 1.3 1.11 Max 7.62 5.06 Max 2.54 Min 0.51 Min $0.25^{+0.13}_{-0.05}$ 0.48 ± 0.10 2.54 ± 0.25 $0^{\circ} - 15^{\circ}$ Hitachi Code DP-16 **JEDEC** Conforms EIAJ Conforms Weight (reference value) 1.07 g

Unit: mm



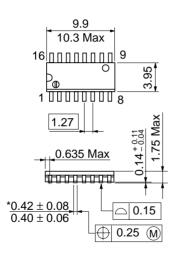


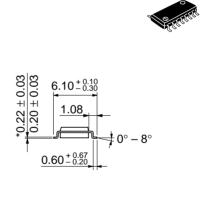


*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DA
JEDEC	_
EIAJ	Conforms
Weight (reference value)	0.24 g

Unit: mm





*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DN
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.15 g

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HTACHI

Hitachi, Ltd.

Semiconductor & Integrated Circuits.

Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

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For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose,CA 95134 Tel: <1> (408) 433-1990 Fax: <1>(408) 433-0223 Hitachi Europe GmbH Electronic components Group Dornacher Stra§e 3 D-85622 Feldkirchen, Munich Germany Tel: <49> (89) 9 9180-0

Fax: <49> (89) 9 29 30 00 Hitachi Europe Ltd. Electronic Components Group. Whitebrook Park Lower Cookham Road Maidenhead

Berkshire SL6 8YA, United Kingdom Tel: <44> (1628) 585000 Fax: <44> (1628) 778322

Hitachi Asia Pte. Ltd. 16 Collyer Quay #20-00 Hitachi Tower Singapore 049318 Tel: 535-2100 Fax: 535-1533

Hitachi Asia Ltd. Taipei Branch Office 3F, Hung Kuo Building. No.167, Tun-Hwa North Road, Taipei (105) Tel: <886> (2) 2718-3666 Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road, Tsim Sha Tsui, Kowloon, Hong Kong Tel: <852> (2) 735 9218

Fax: <852> (2) 730 0281 Telex: 40815 HITEC HX

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